

ABSTRACT OF THE DISCLOSURE

There is provided a semiconductor device comprising a semiconductor chip whose main surface comprises first electrode pads; a wiring portion electrically connected to the electrode  
5 pad and including a bump portion that protrudes upward in a vertical direction with respect to the main surface; a sealing layer covering the perimeter and main surface of the chip; and a re-distribution wiring layer which electrically connected to the wiring portion and extending from a first portion of the  
10 sealing layer over the main surface to a second region of the sealing layer outside the first region.